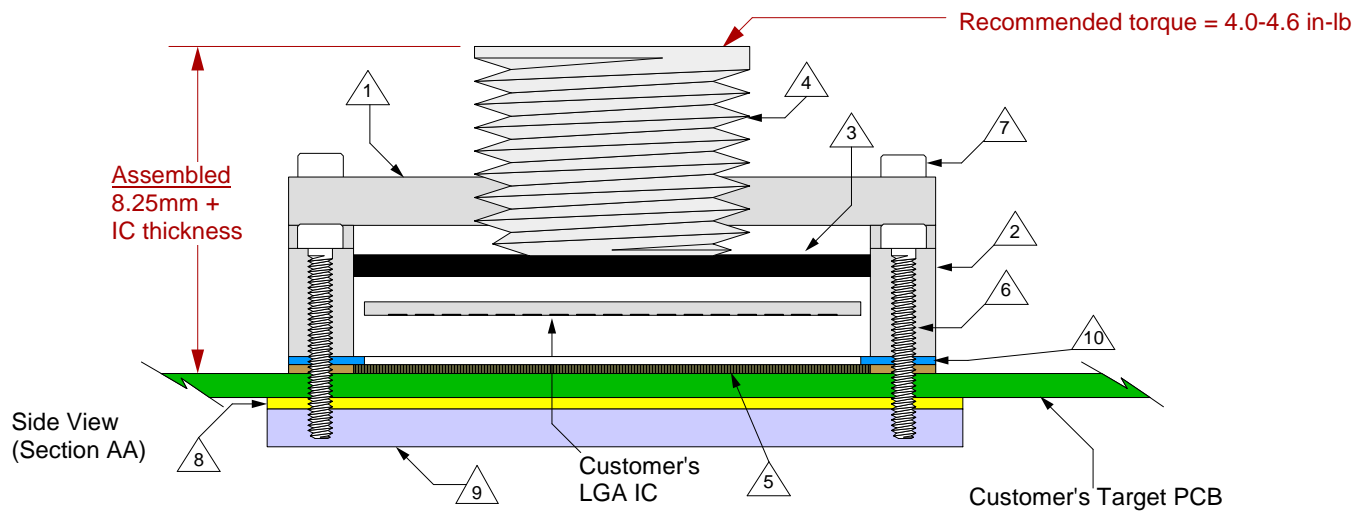
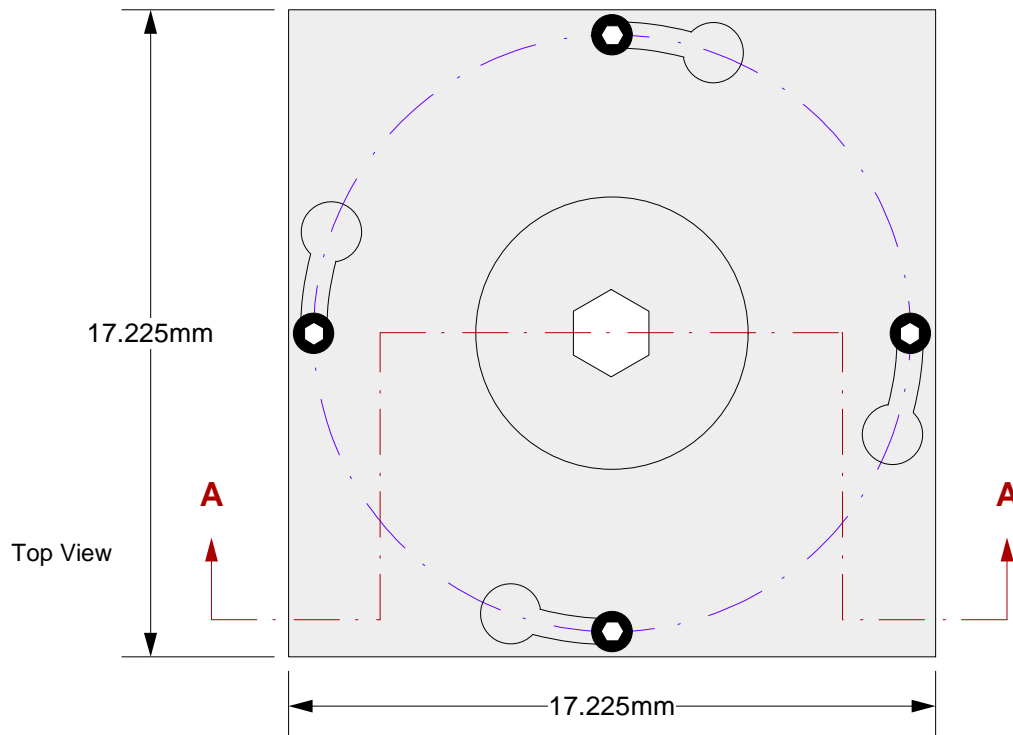


40 GHz LGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Interposer: Copper plated kapton and conductive elastomer. Thickness = 0.363mm.
- △ 6 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 7 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 8 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 9 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.
- △ 10 IC Guide: Kapton

XG-LGA-7000 Drawing

Status: Released

Scale: -

Rev: B



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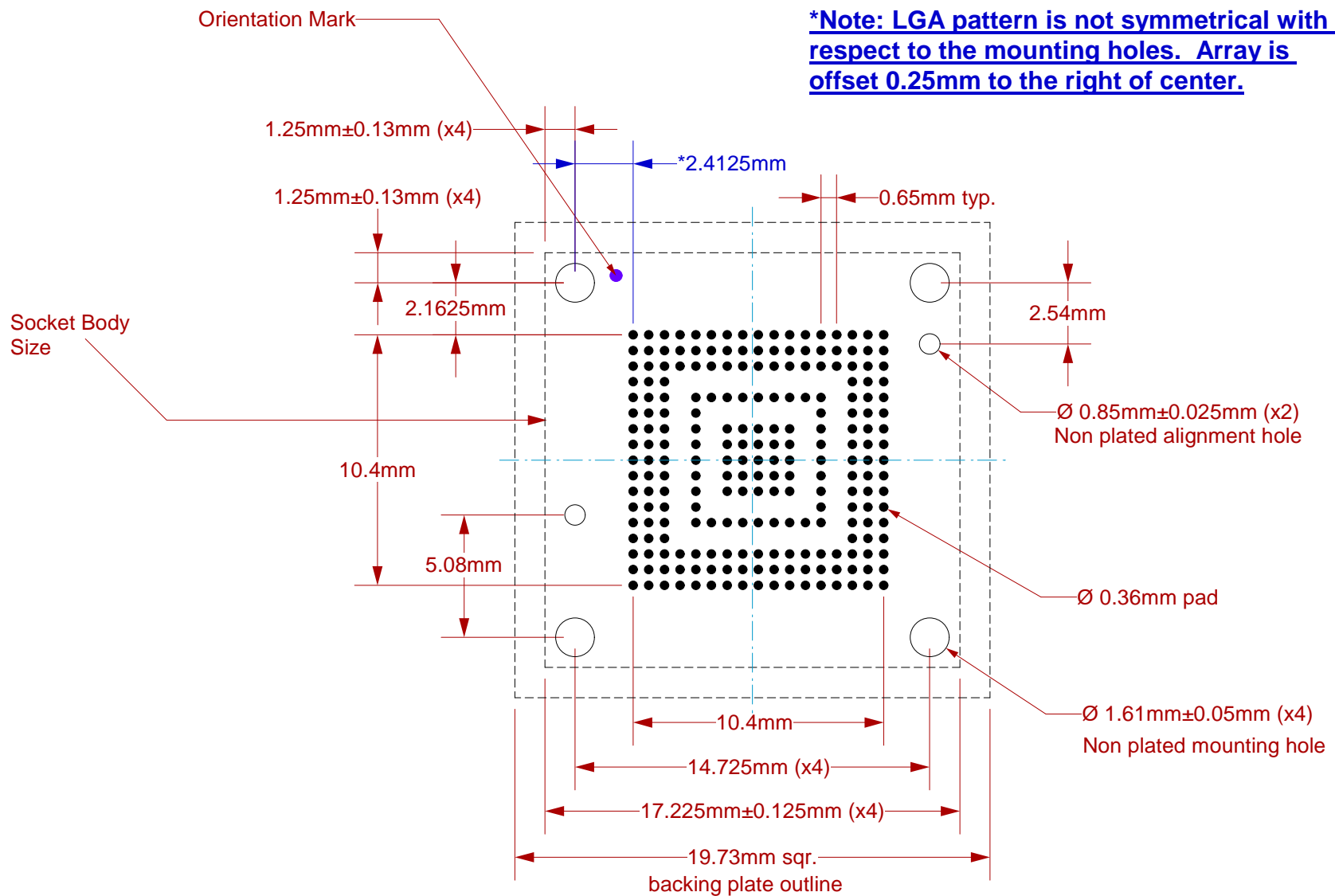
Drawing: J. Glab

Date: 02/11/08

File: XG-LGA-7000 Dwg

Modified: 8/3/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.



Target PCB Recommendations


Total thickness: 1.6mm min.

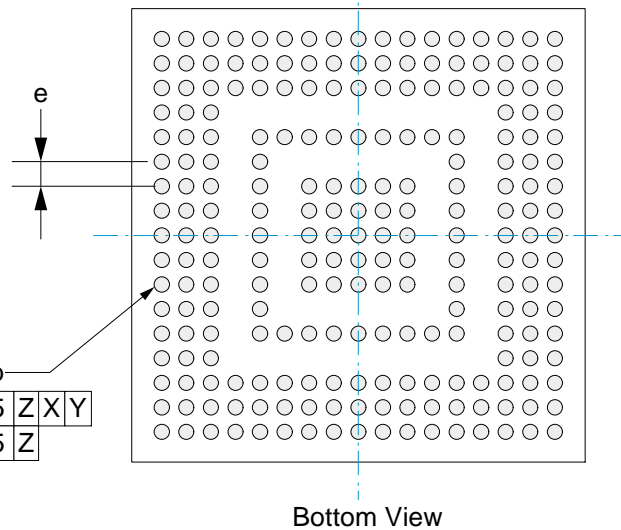
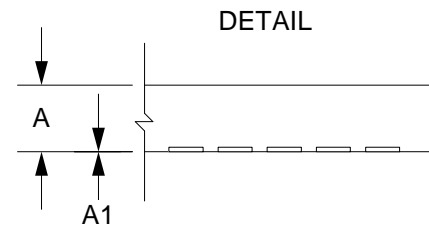
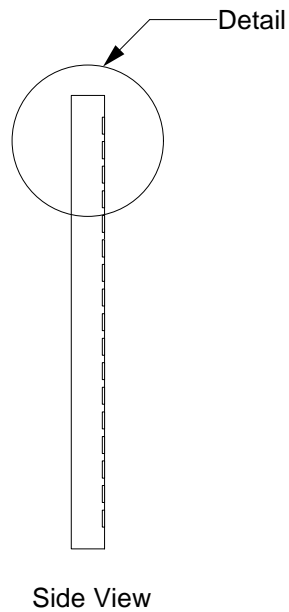
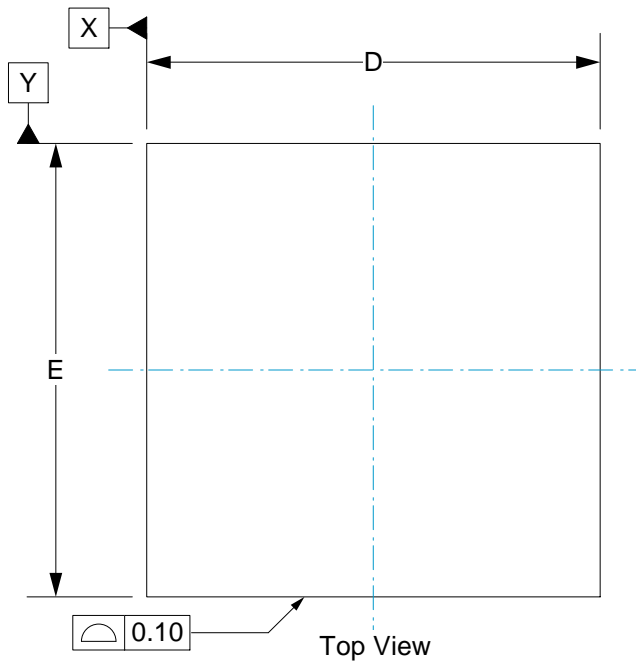
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	XG-LGA-7000 Drawing		Status: Released	Scale: 4:1	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (800) 404-0204 www.ironwoodelectronics.com		Drawing: J. Glab	Date: 02/11/08	
			File: XG-LGA-7000 Dwg	Modified: 8/3/09, AE	



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

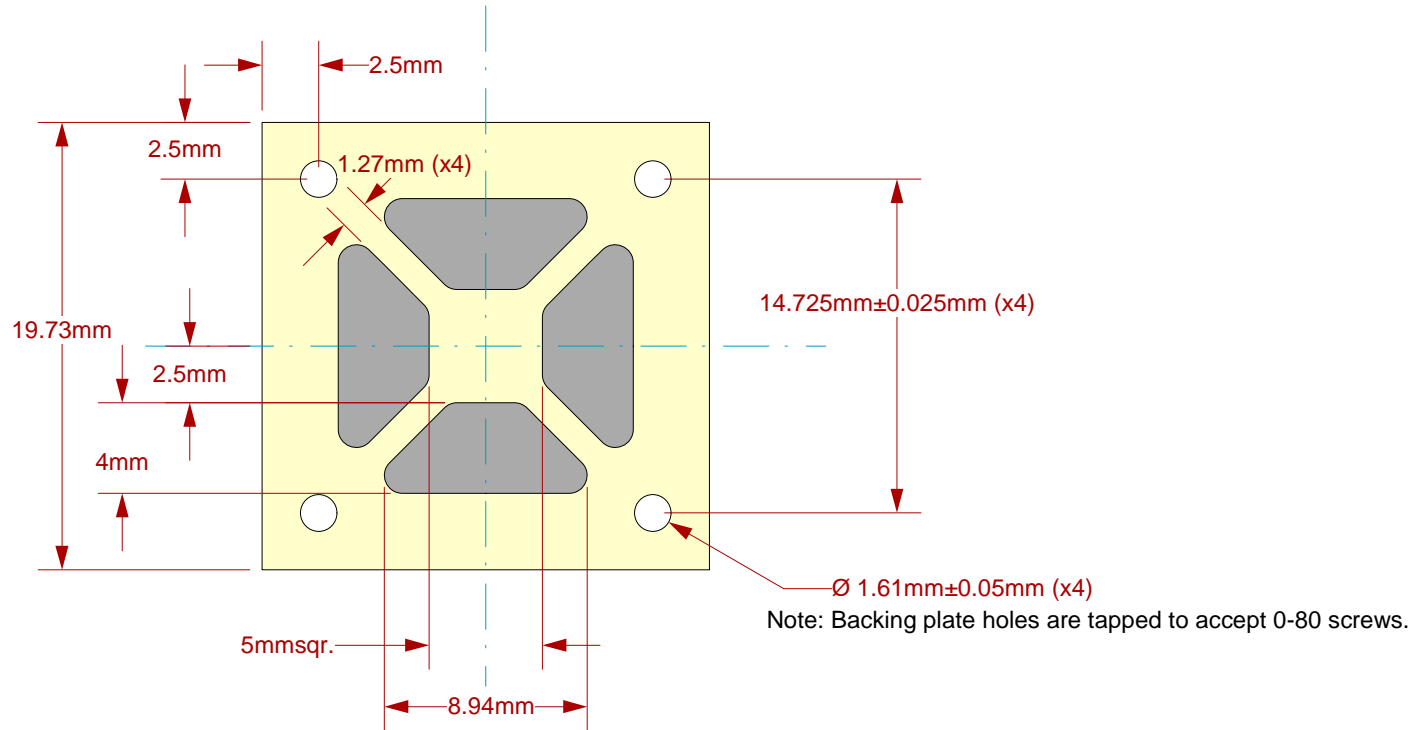
Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

DIM	MIN	MAX
A		0.61
A1		0
b		0.35
D	12.0 BSC	
E	12.0 BSC	
e	0.65 BSC	

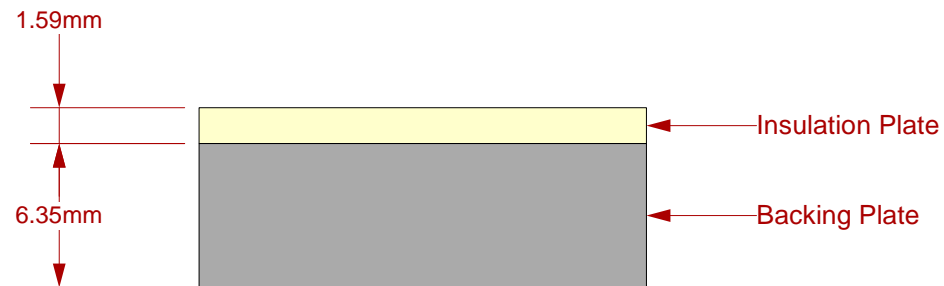
17 x 17 array

	XG-LGA-7000 Drawing	Status: Released	Scale: -	Rev: B
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		File: XG-LGA-7000 Dwg	Modified: 8/3/09, AE	


Top View



Side View



Description: Insulation Plate and Backing Plate

	XG-LGA-7000 Drawing	Status: Released	Scale: 3:1	Rev: B
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		File: XG-LGA-7000 Dwg		Modified: 8/3/09, AE

All dimensions are in mm.
 All tolerances are $\pm 0.125\text{mm}$.
 (Unless stated otherwise)